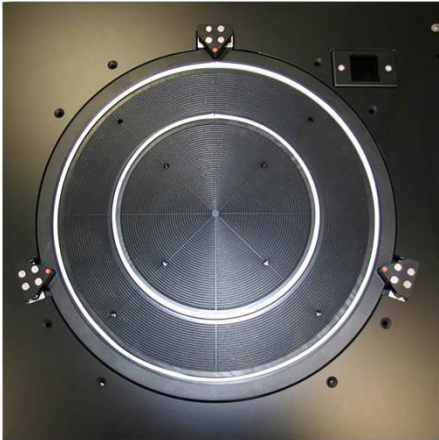


Lift-pin (vacuum) chuck

mV- Chuck Series



Features

- available for different eWLB wafer sizes (8"/12"/13")
- maximum warpage compatible
- lift pins on outer wafer perimeter or in centre area
- controlled vacuum flow

ASK FOR YOUR CUSTOMIZED SOLUTION!

Functional description

mechatronic vacuum chucks (mVC) are designed for secure placement of various wafer types (eg. standard, (ultra-)thin/warped, eWLB, Taiko, film-frame, MEMS) in a defined orientation. These chucks are mainly integrated in OEM-equipment (eg. for inspection measurement, defect detection, ...) under atmospheric conditions.

Lift-pin chucks are designed for planarization of various wafer types (e.g. eWLB). Due to patented seal design a controlled vacuum force is applied to flatten the warped wafer.

Loading	Automated or manual from top side
Wafer detection	Vacuum
Centering accuracy (X, Y axis)	n.a.
Suitable End- effector	Top Grip End- effector, Contactless End- effector, Needle End- effector, Vacuum End- effector;
Materials	Stainless steel, anodized aluminum, PEEK, NBR, porous ceramic;
Pneumatic	
Pneumatic media	CDA and Vacuum
Supply pressure	5.5- 6.5 bar
Supply Vacuum	-85 kPa

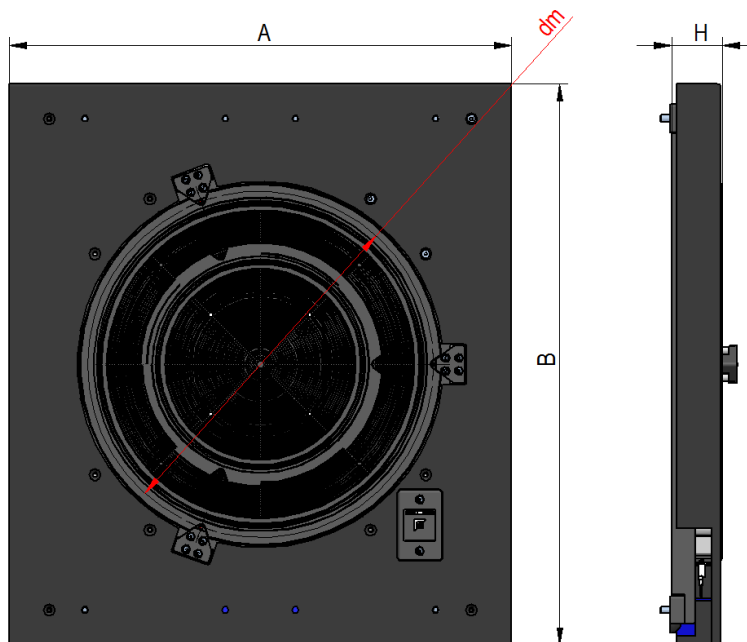
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Lift-pin (vacuum) chuck

mV- Chuck Types & sizes

Type	mV- Chuck 200	mV- Chuck 300	mV- Chuck 300
Wafer size	200 mm (8")	300 mm (12")	330 mm (13")
Wafer thickness	> 300 µm (11.8 mil)	> 300 µm (11.8 mil)	> 300 µm (11.8 mil)
Warpage (depends on wafer thickness)	+ - 3 mm	+ - 6 mm	+ - 6 mm
Weight	5800 g	n.a.	n.a.
dm (diameter)	196 mm	296 mm	326 mm
H (height)	40 mm	43 mm	43 mm
A	285 mm	430 mm	430 mm
B	324 mm	480 mm	480 mm
Lift pin stroke	14 mm (other stroke an request)		

Special customized designs available!



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